



Model : CBGA0127271007-A2

BGA Heat Sink Specification

For 27x27 Chip set

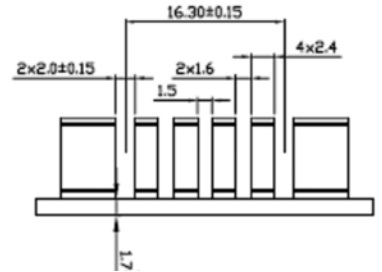
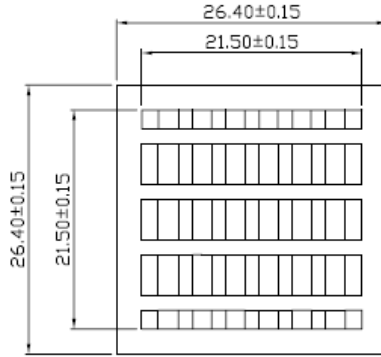


1. Material : Al 6063

2. Dimension :
Foot print : 27x27mm
Height : 10 mm
Base (thickness) : 1.7mm

3. Finish: Black Anodize

4. Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : 8612I or others



Performance

| | |
|-------------------|-------|
| Heat Source (LxW) | 15x15 |
|-------------------|-------|

